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(12) **United States Design Patent**  
**Soyano**

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(54) **SEMICONDUCTOR**

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(\*\*) **Term:** **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/110,

D13/182; 257/690; 361/713, 728, 736, 775

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a semiconductor, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of front, top plan and right side of a semiconductor showing our new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a top plan view thereof;

FIG. 5 is a bottom view thereof;

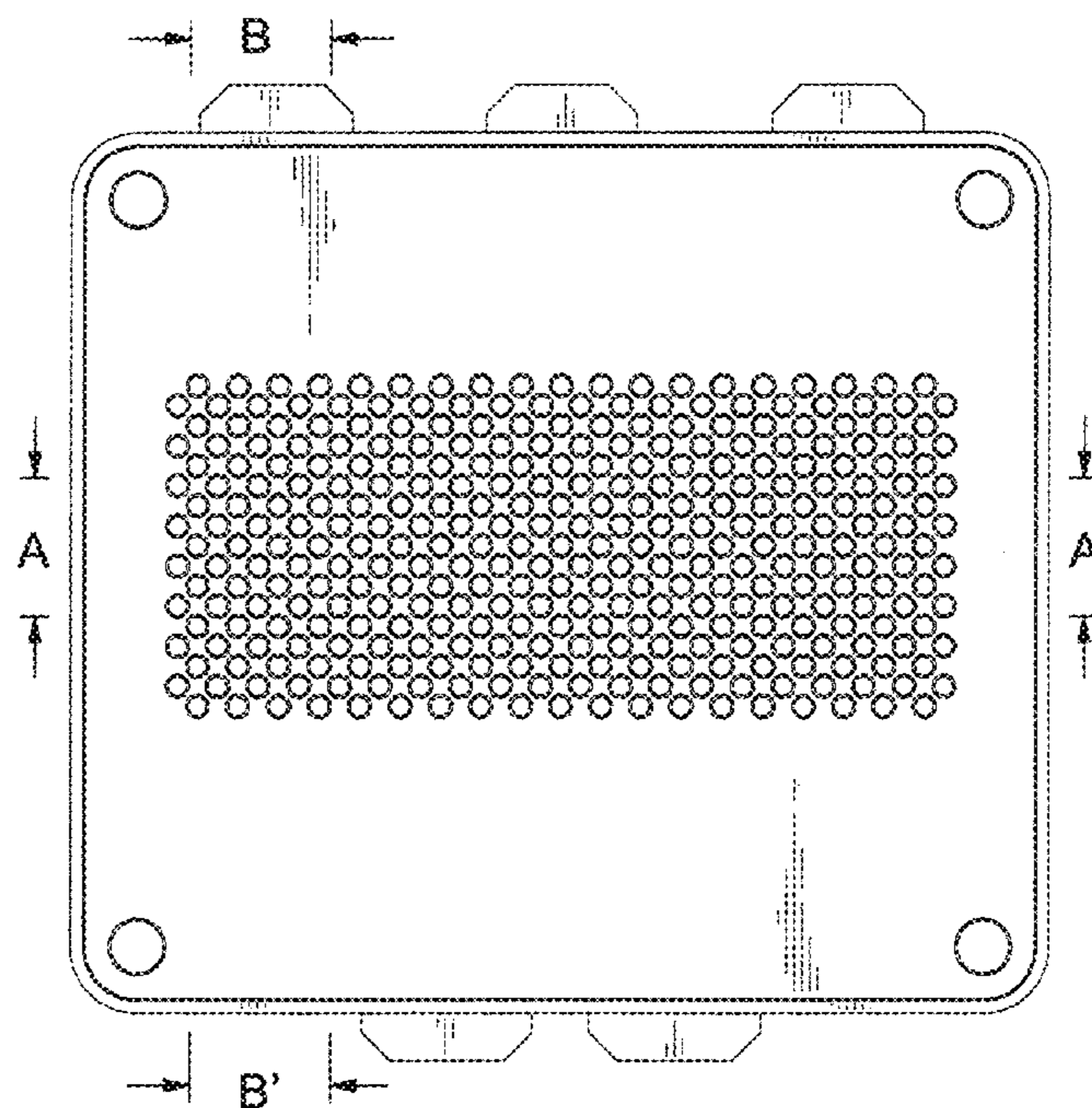
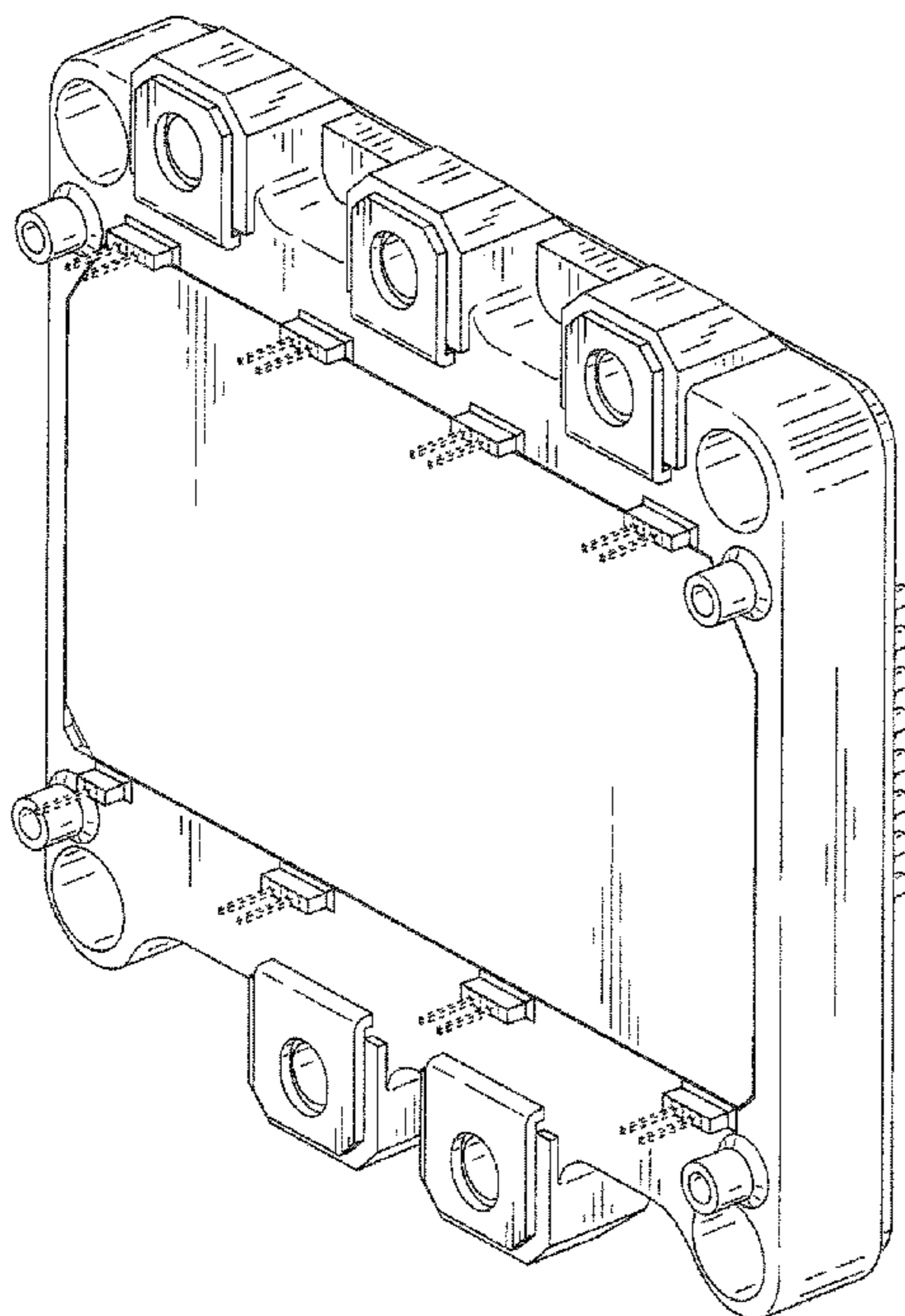
FIG. 6 is a left side view thereof;

FIG. 7 is a right side view thereof; and,

FIG. 8 is a partial enlarged view at A-A', B-B' thereof.

The portions of the article in broken lines are shown for illustrative purposes only and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



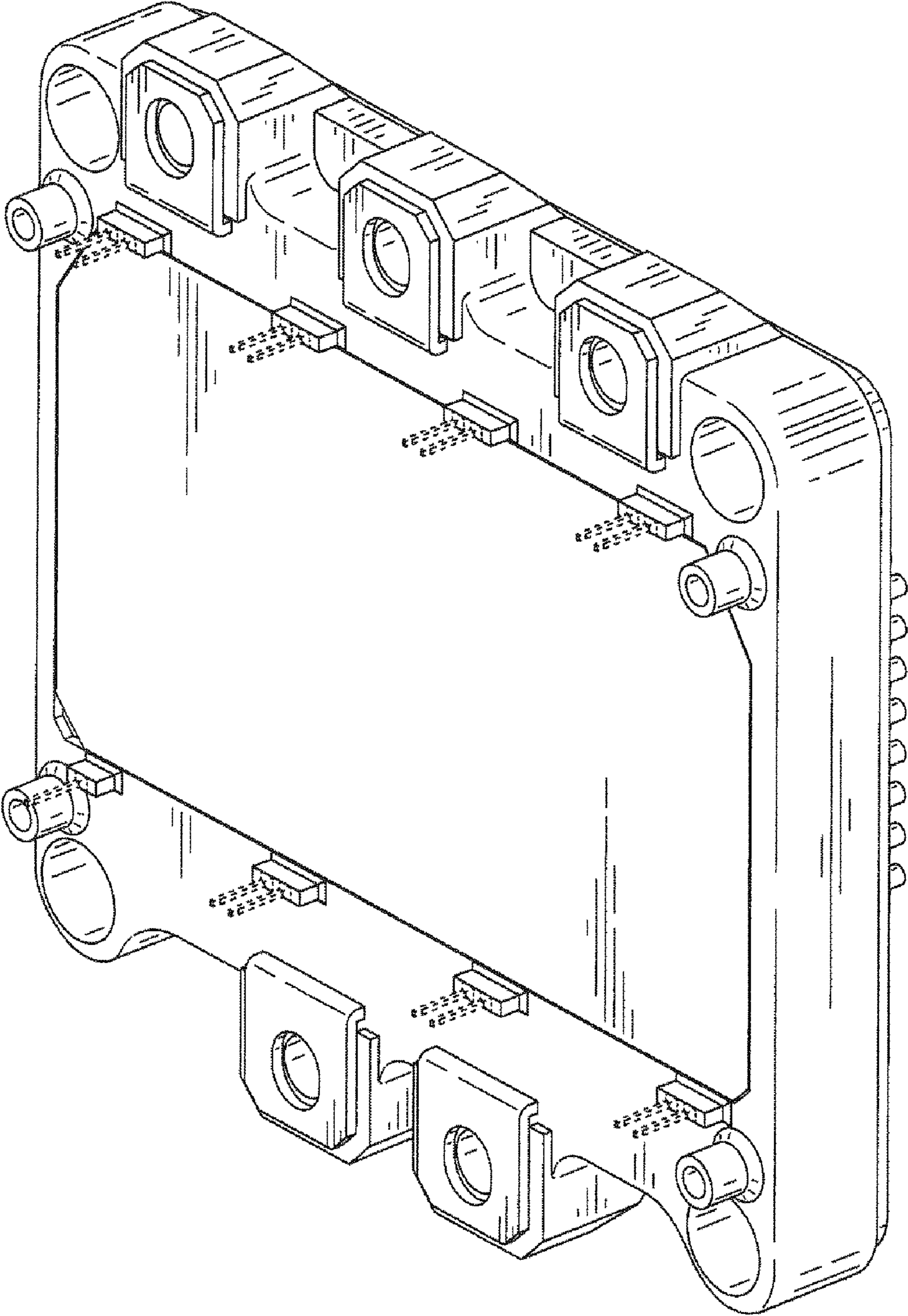


FIG. 1

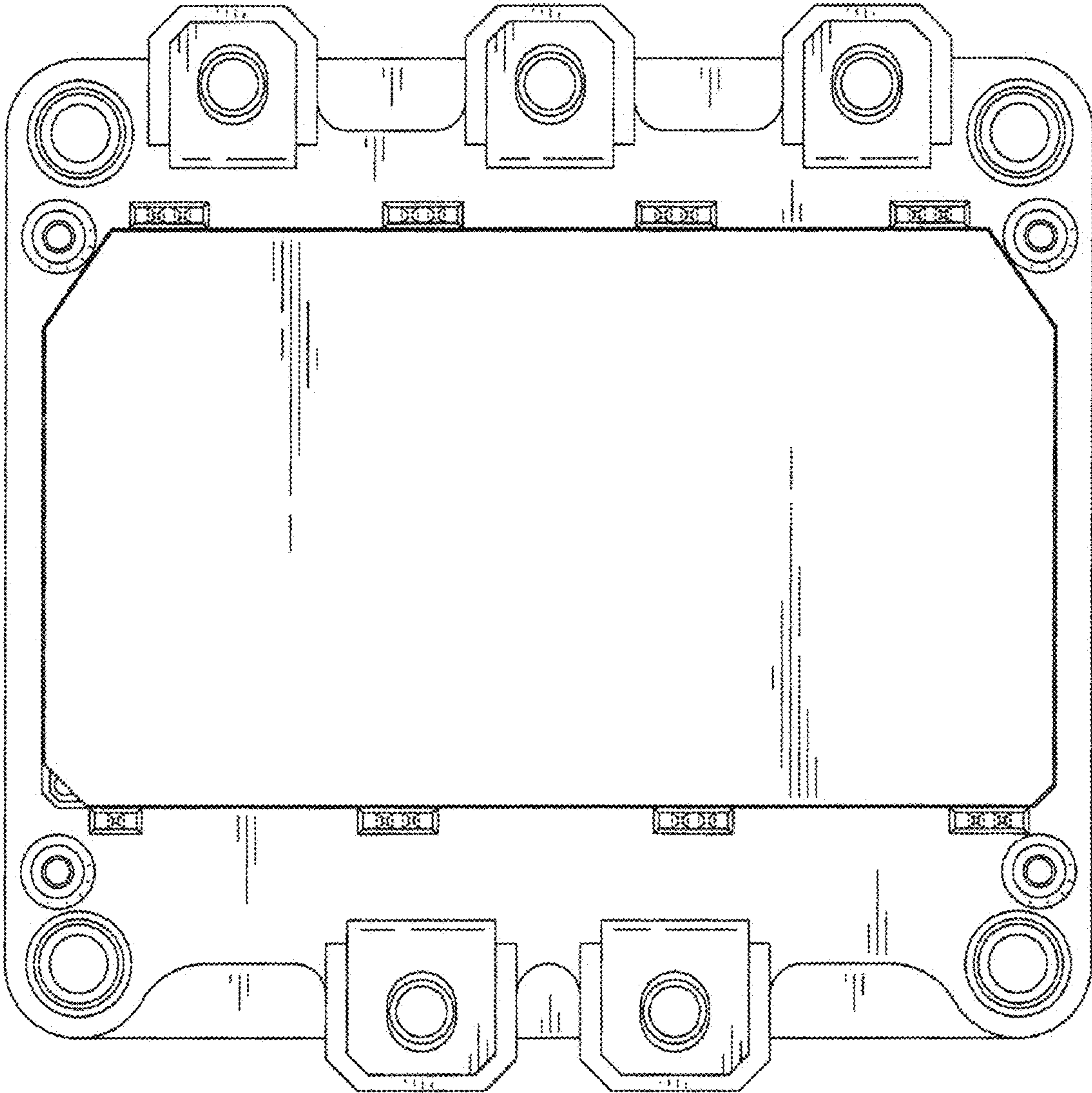


FIG. 2

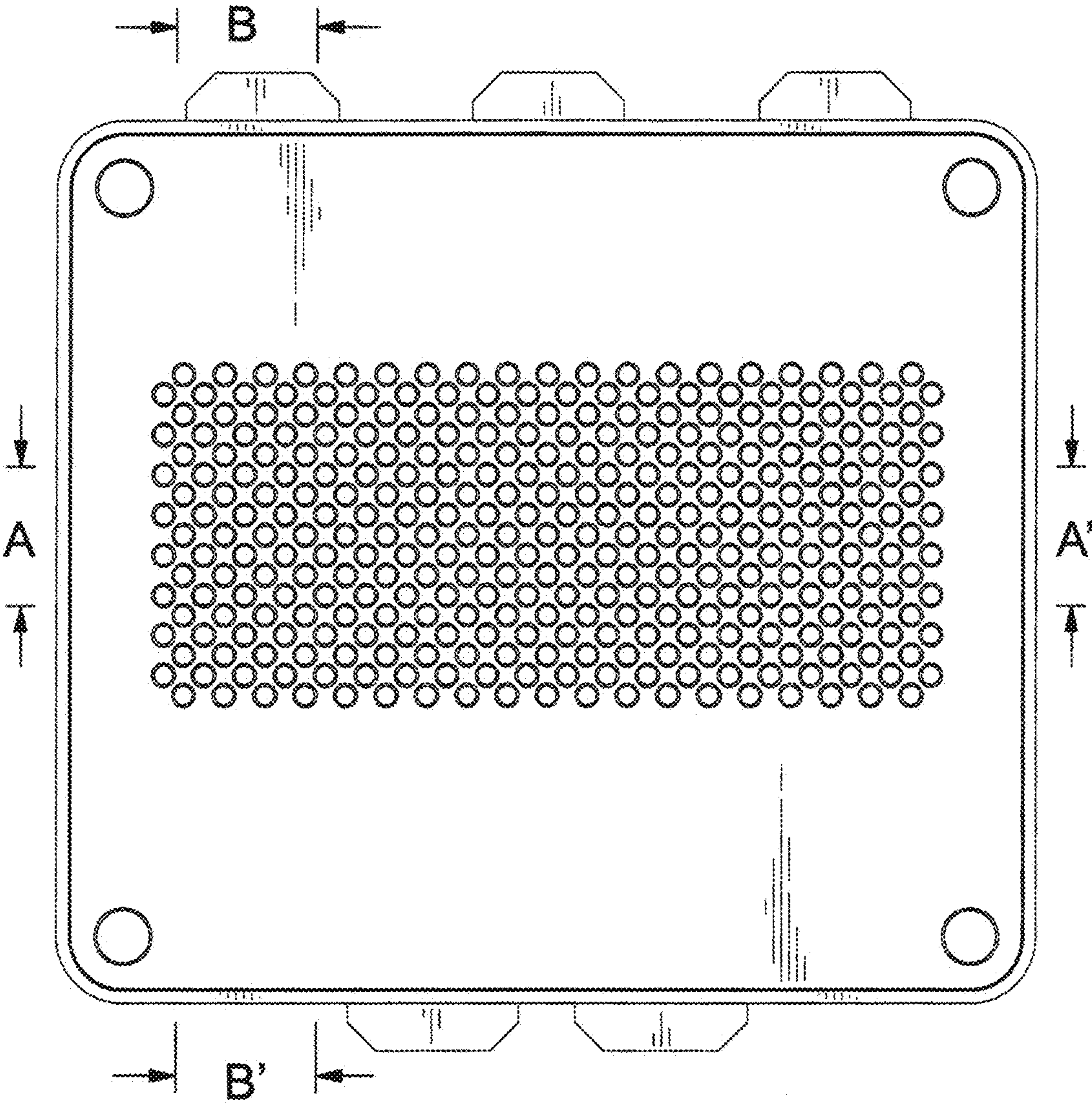


FIG. 3

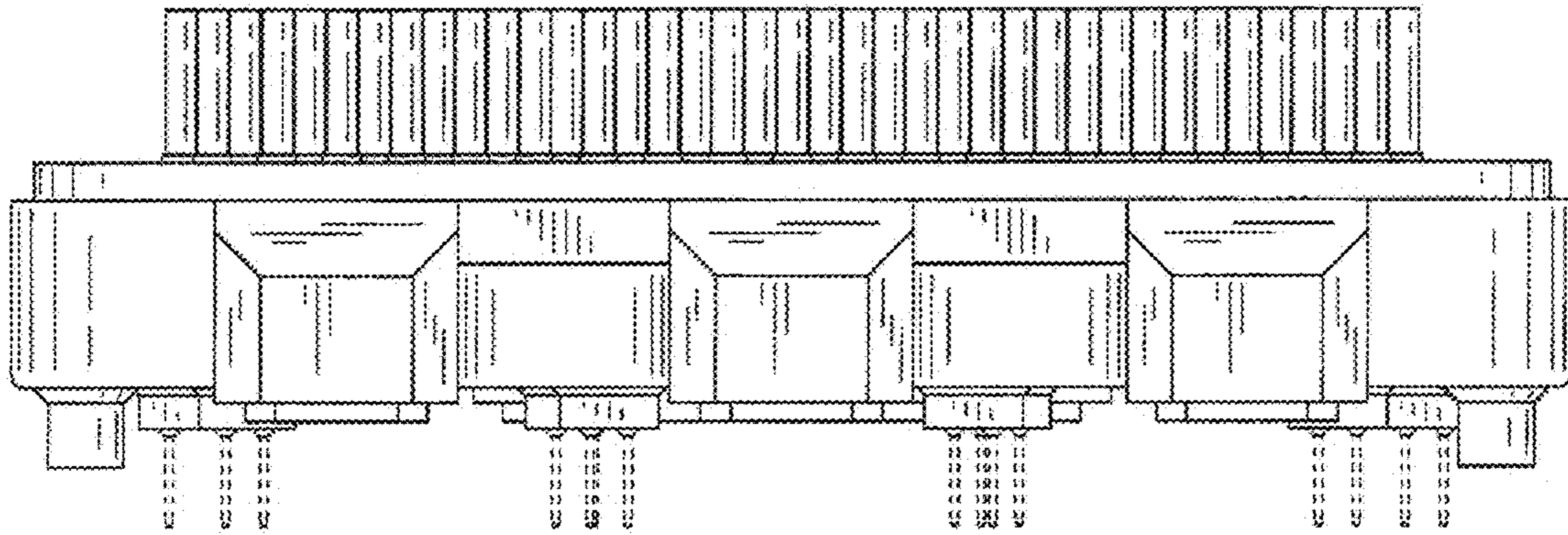


FIG. 4

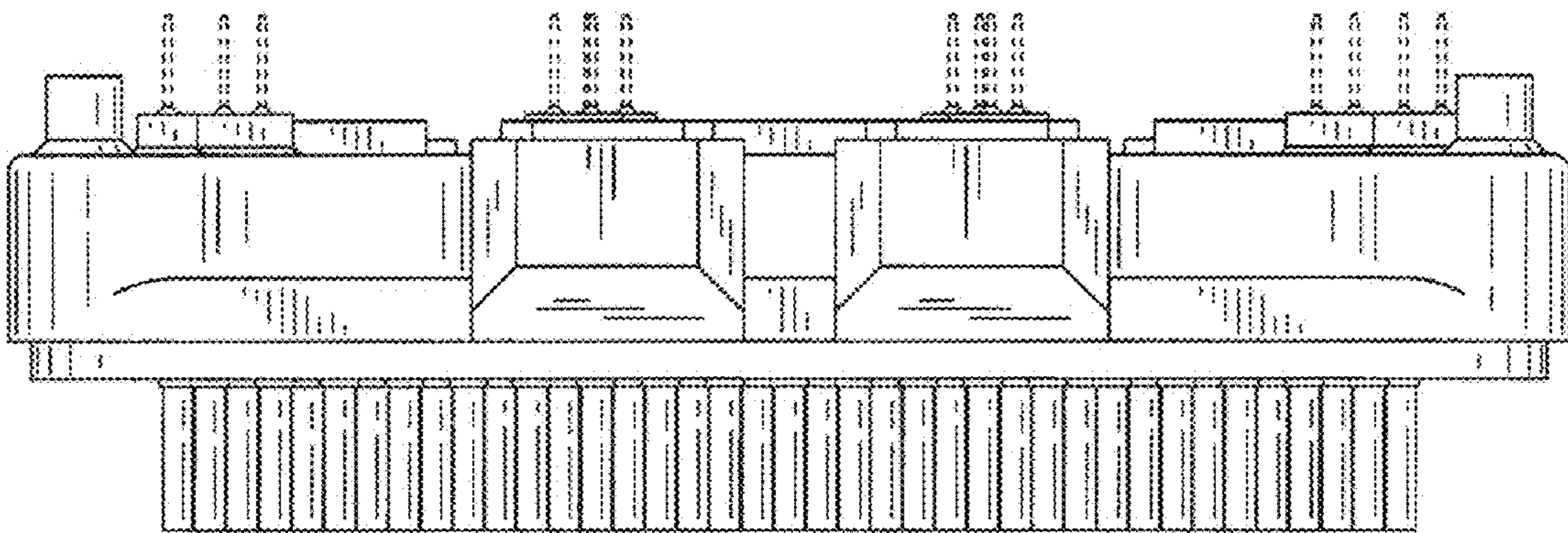


FIG. 5

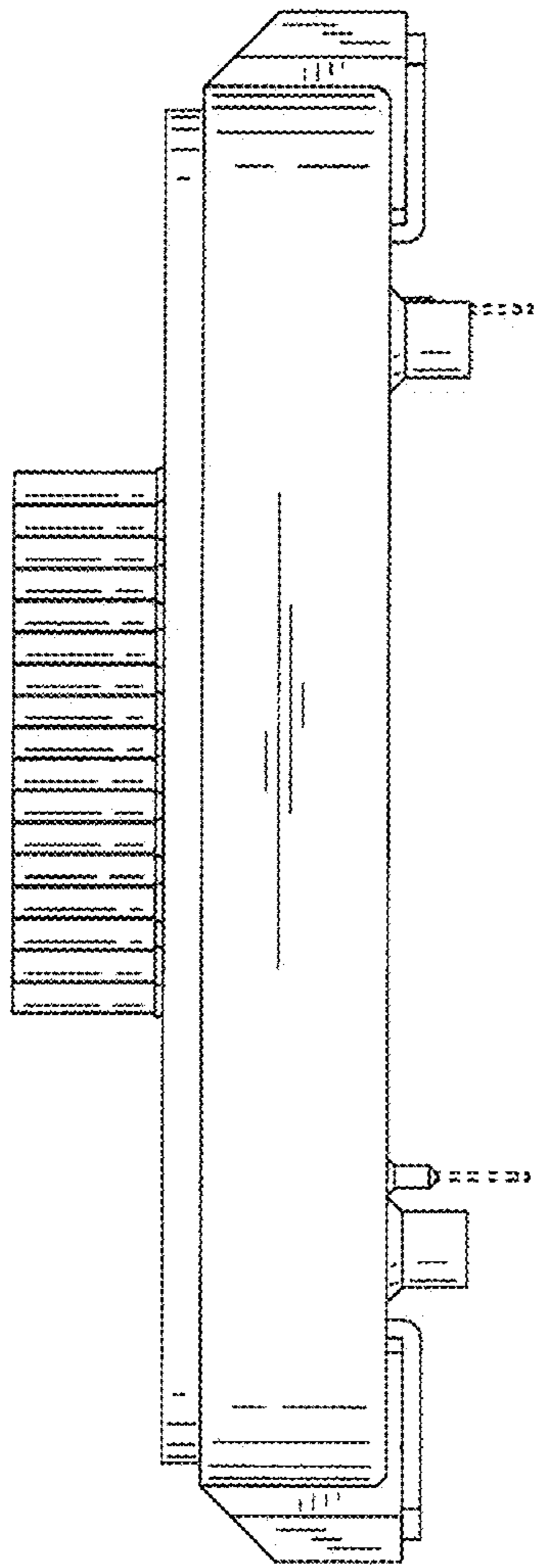


FIG. 6

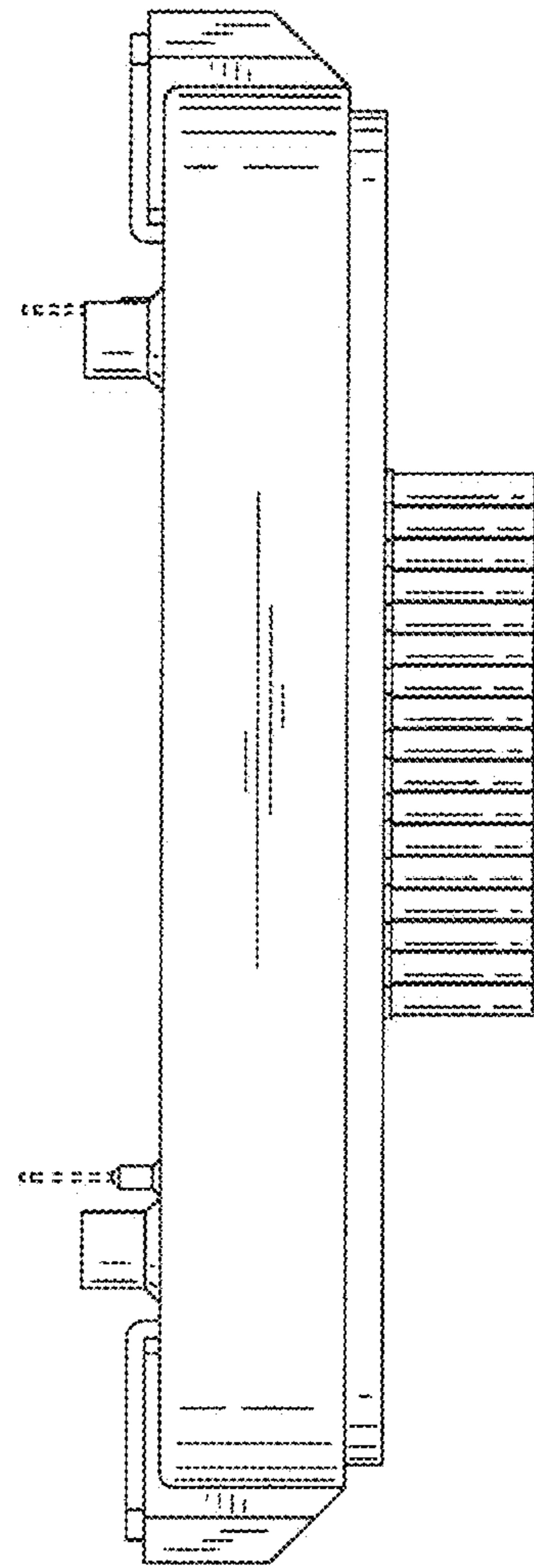
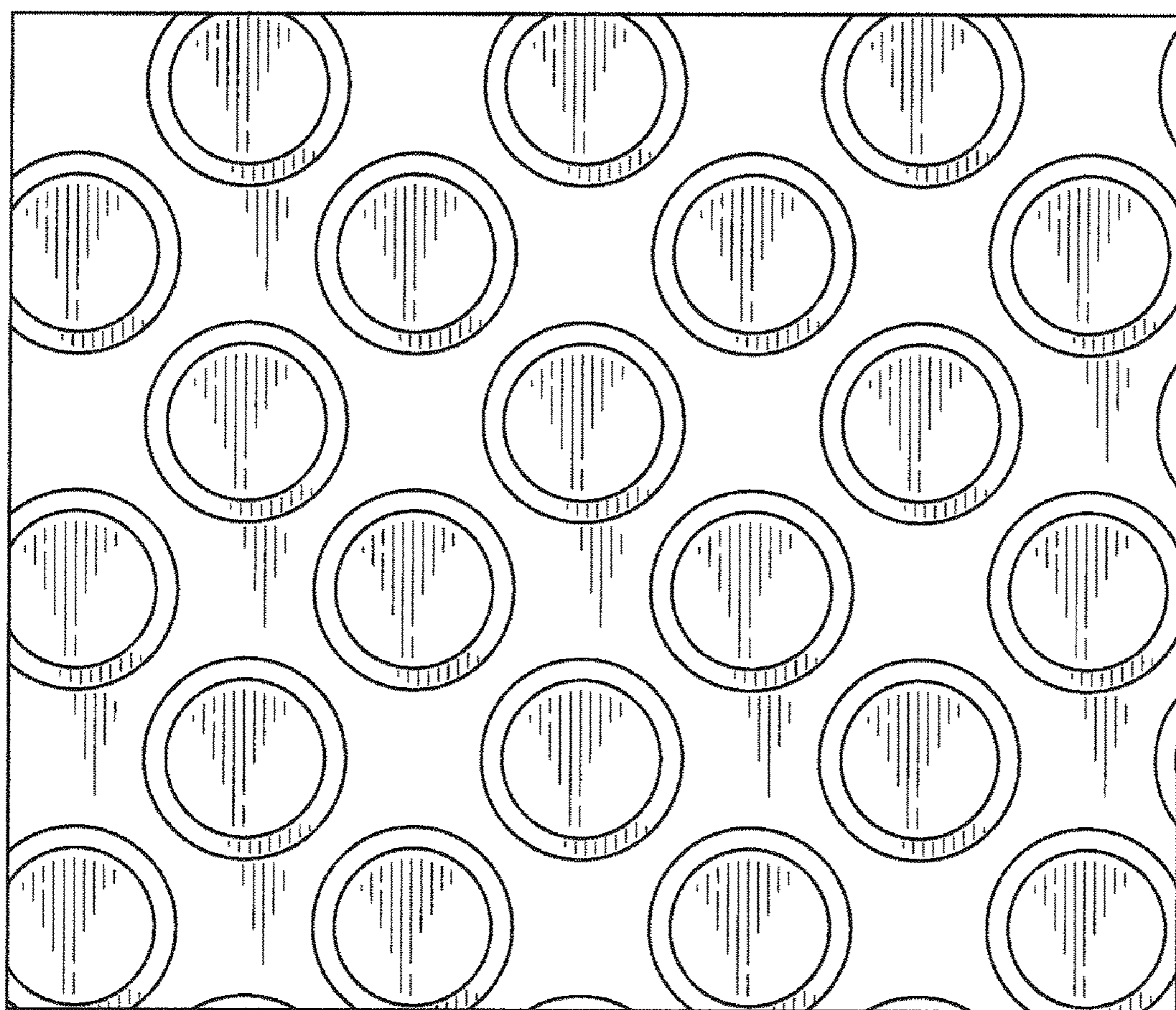


FIG. 7



**FIG. 8**